

Dual N-Channel Advanced Power MOSFET

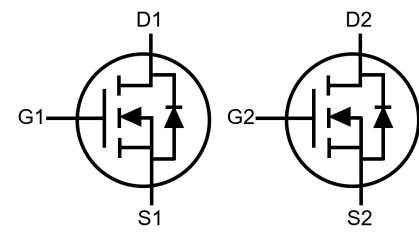
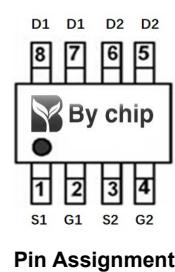
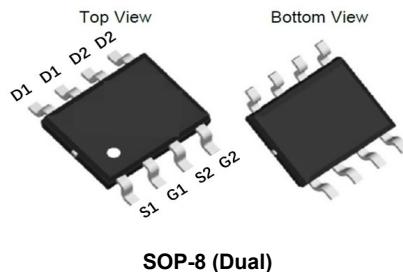
Features

- $V_{DS} = 60V$, $I_D = 9A$
- $R_{DS(ON)} < 14\text{ m}\Omega @ V_{GS} = 10V$
- $R_{DS(ON)} < 18\text{ m}\Omega @ V_{GS} = 4.5V$

General Features

- Advanced Trench Technology
- Provide Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free and Green Available

100% UIS TESTED!
100% ΔV_{ds} TESTED!



Absolute Maximum Ratings $T_C = 25^\circ C$, unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Continuous Drain Current	I_D	9	A
Pulsed Drain Current	I_{DM}	36	A
Gate-Source Voltage	V_{GS}	± 20	V
Power Dissipation	P_D	2.6	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 To 150	$^\circ C$

Thermal Resistance

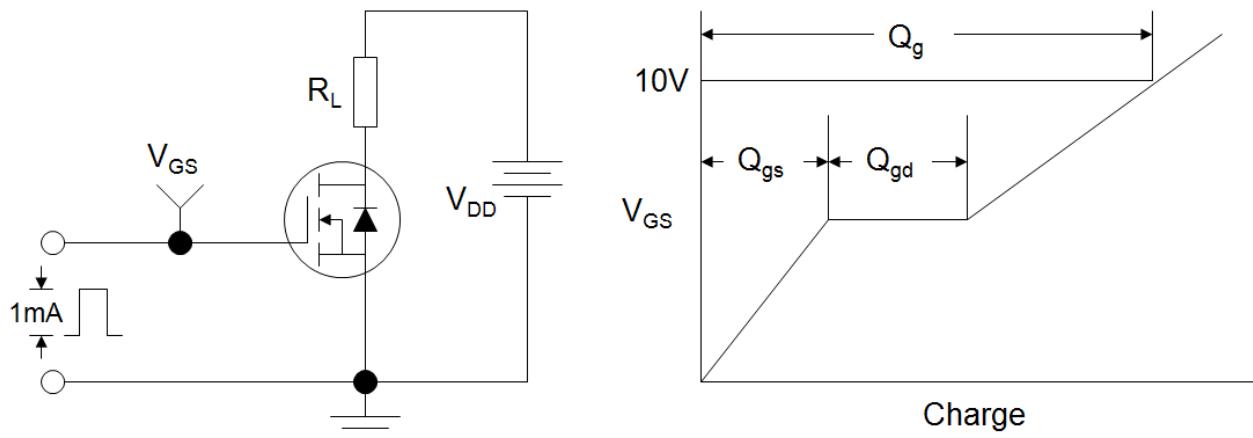
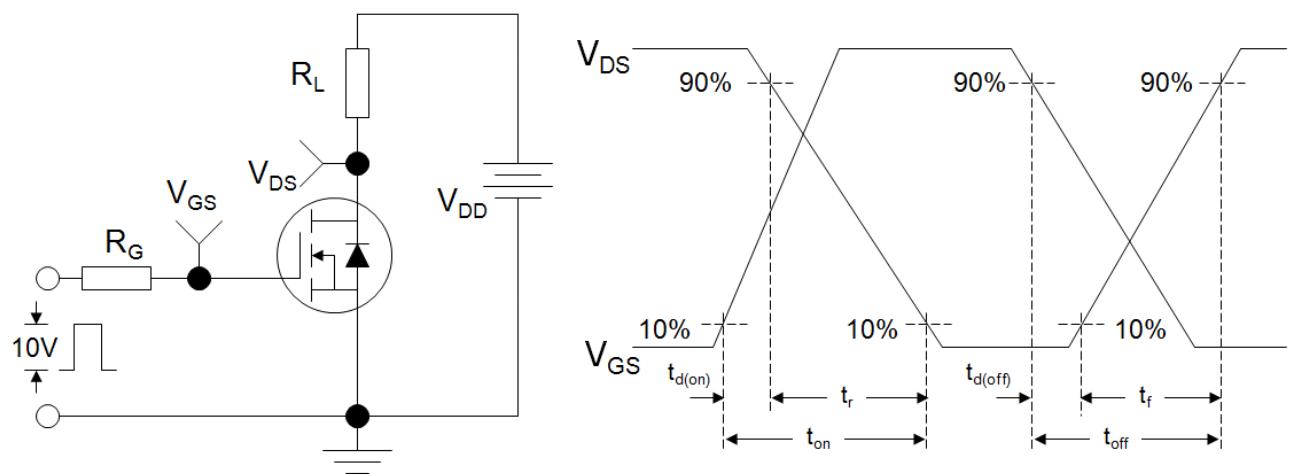
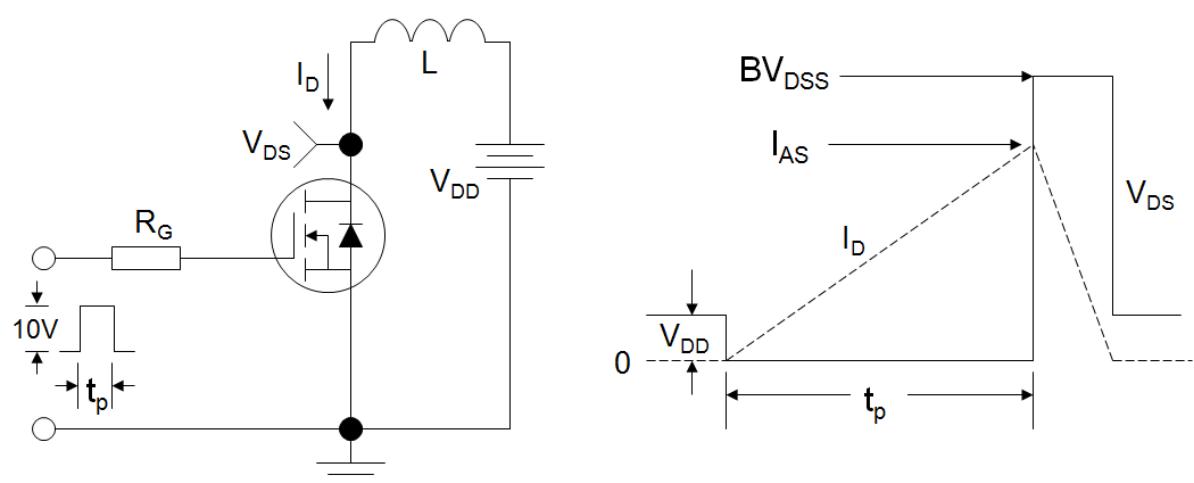
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	R_{thJA}	48	$^\circ C/W$

Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	60	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 60\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 25^\circ\text{C}$	--	--	1	μA
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.0		2.5	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 9\text{A}$	--		14	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 9\text{A}$	--		18	
Forward Transconductance	g_{FS}	$V_{\text{DS}}=5\text{V}, I_D=9\text{A}$	25	--	--	S
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 30\text{V}, f = 1.0\text{MHz}$	--	2180	--	pF
Output Capacitance	C_{oss}		--	350	--	
Reverse Transfer Capacitance	C_{rss}		--	270	--	
Total Gate Charge	Q_g	$V_{\text{DD}} = 30\text{V}, I_D = 9\text{A}, V_{\text{GS}} = 10\text{V}$	--	47	--	nC
Gate-Source Charge	Q_{gs}		--	6.7	--	
Gate-Drain Charge	Q_{gd}		--	12.5	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 30\text{V}, I_D = 9\text{A}, R_G = 3\Omega$	--	8.5	--	ns
Turn-on Rise Time	t_r		--	6	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	30	--	
Turn-off Fall Time	t_f		--	5	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	9	A
Pulsed Diode Forward Current	I_{SM}		--	--	36	
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 9\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.2	V

Notes

- Repetitive Rating: Pulse width limited by maximum junction temperature
- Identical low side and high side switch with identical R_G

Gate Charge Test Circuit**Switch Time Test Circuit****EAS Test Circuit**

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

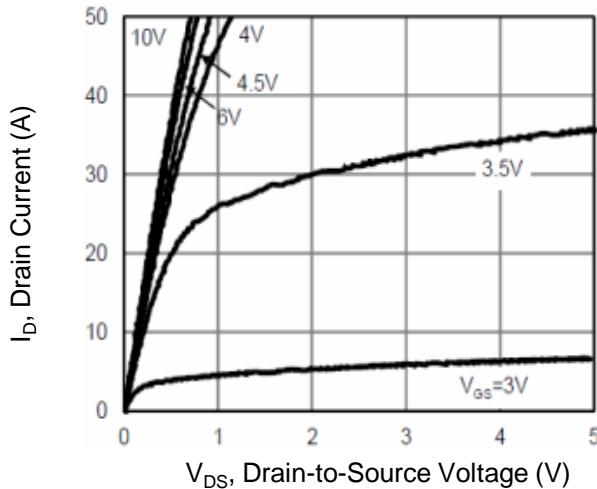


Figure 2. Transfer Characteristics

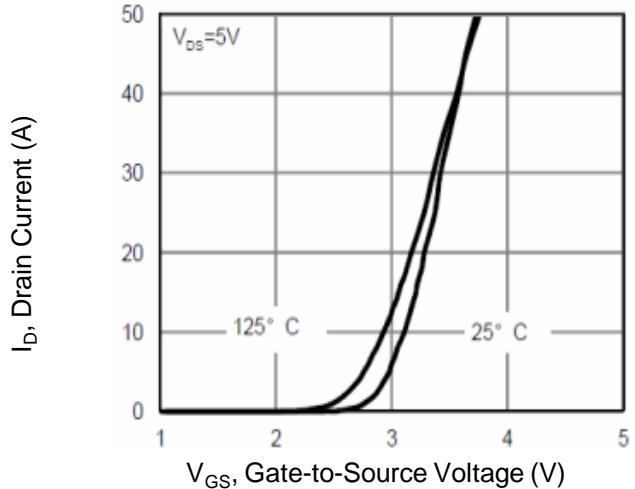


Figure 3. On-Resistance vs. Drain Current

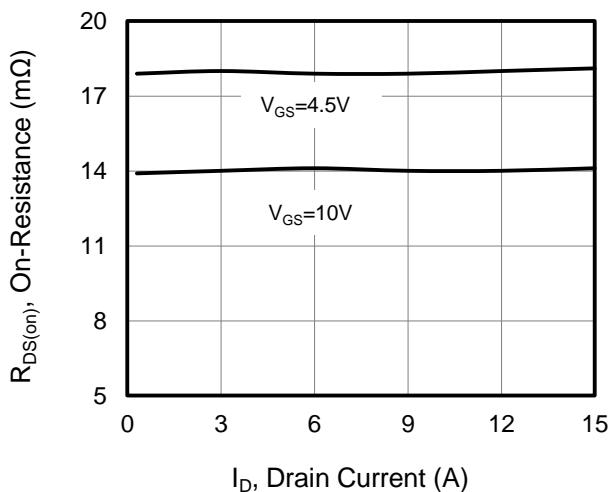


Figure 4. Gate Charge

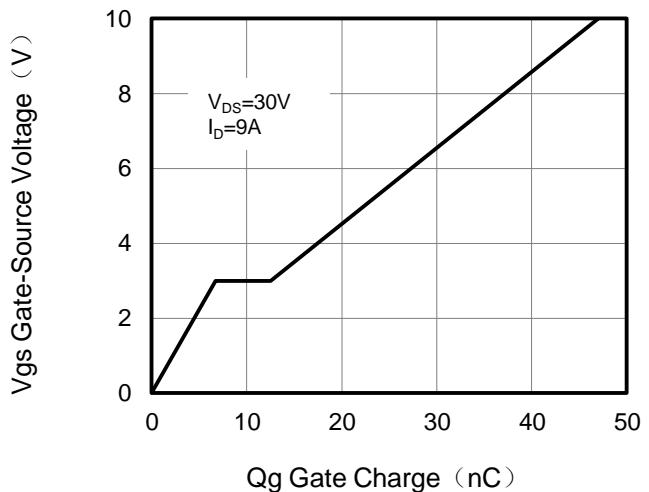


Figure 5. Capacitance

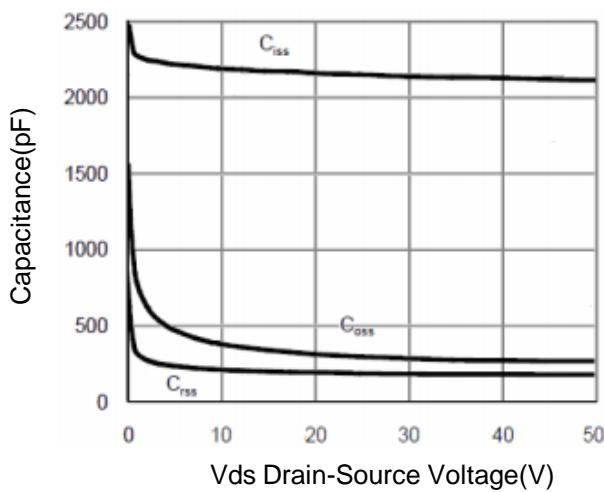
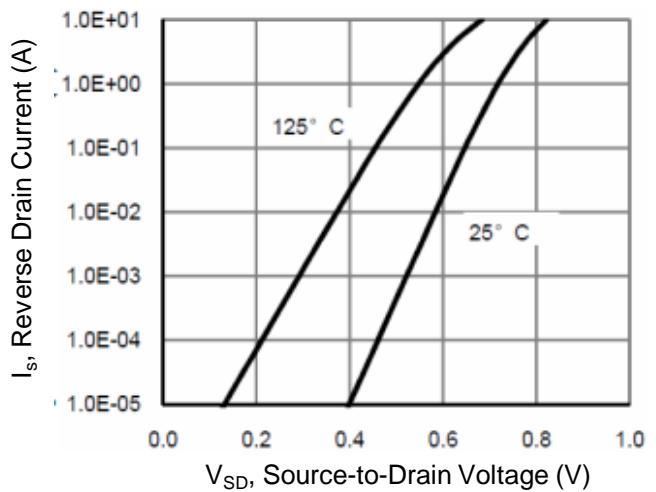


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

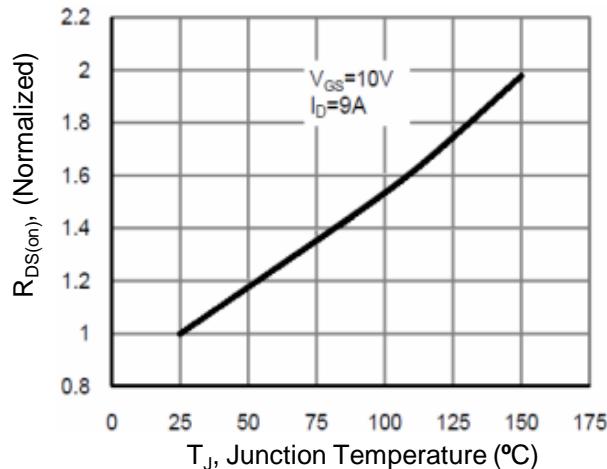


Figure 8. Safe Operation Area

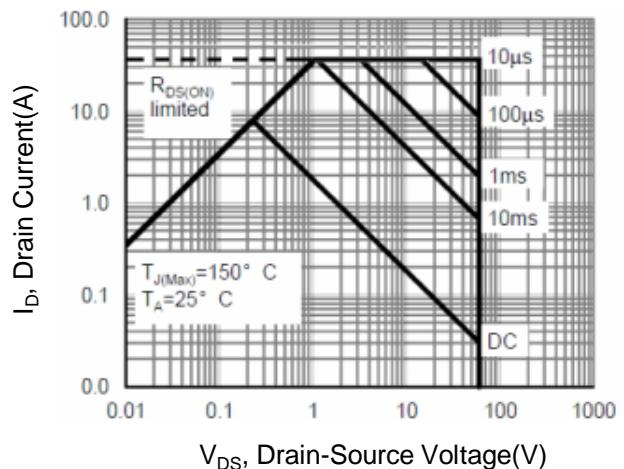


Figure 9. Normalized Maximum Transient Thermal Impedance

